

Features

- Single line bidirectional protection
- Very low capacitance (3 pF typical)
- Lead-free package
- Very low capacitance, line to ground, for optimized data integrity
- Low PCB space consumption: 0.6 mm² max
- No insertion loss in AM and FM band
- High reliability offered by monolithic integration

Complies with the following standards

- IEC 61000-4-2:
 - 15 kV (air discharge)
 - 8 kV (contact discharge)
- MIL STD 883G- Method 3015-7: class 3B:

Applications

Where transient over voltage protection in ESD sensitive equipment is required, such as:

- Portable audio systems
- Communication systems
- Cellular phone handsets and accessories
- Audio and video equipment

Description

The ESDARF01-1BM2 is a monolithic application specific device dedicated to ESD protection of the AM and FM antenna in cell phones and portable equipment.

The device is ideal for applications where both reduced printed circuit board space and power absorption capability are required.

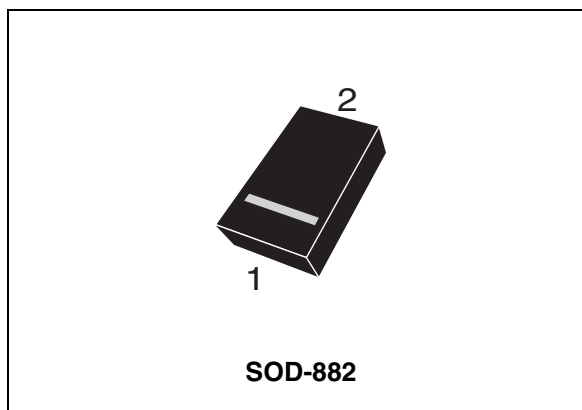
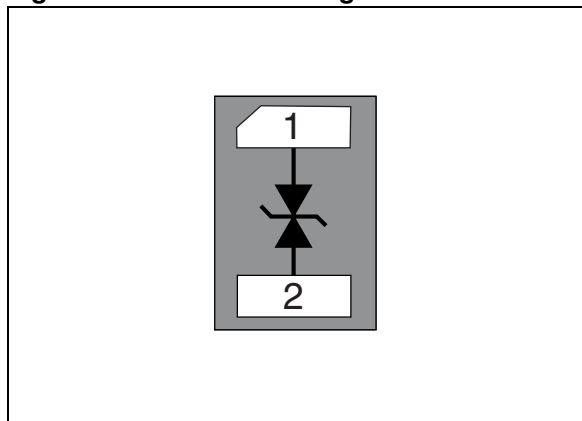


Figure 1. Functional diagram



1 Characteristics

Table 1. Absolute maximum ratings

| Symbol | Parameter | | Value | Unit |
|----------------|---|--|--------------|------|
| $V_{PP}^{(1)}$ | Peak pulse voltage | IEC 61000-4-2 contact discharge IEC 61000-4-2 air discharge | 8 15 | kV |
| T_j | Maximum operating junction temperature | | 125 | °C |
| T_{stg} | Storage temperature range | | - 55 to +150 | °C |
| T_L | Maximum lead temperature for soldering during 10 s at 5 mm for case | | 260 | °C |

1. For a surge greater than the maximum values, the diode will fail in short-circuit.

Figure 2. Electrical characteristics (definitions)

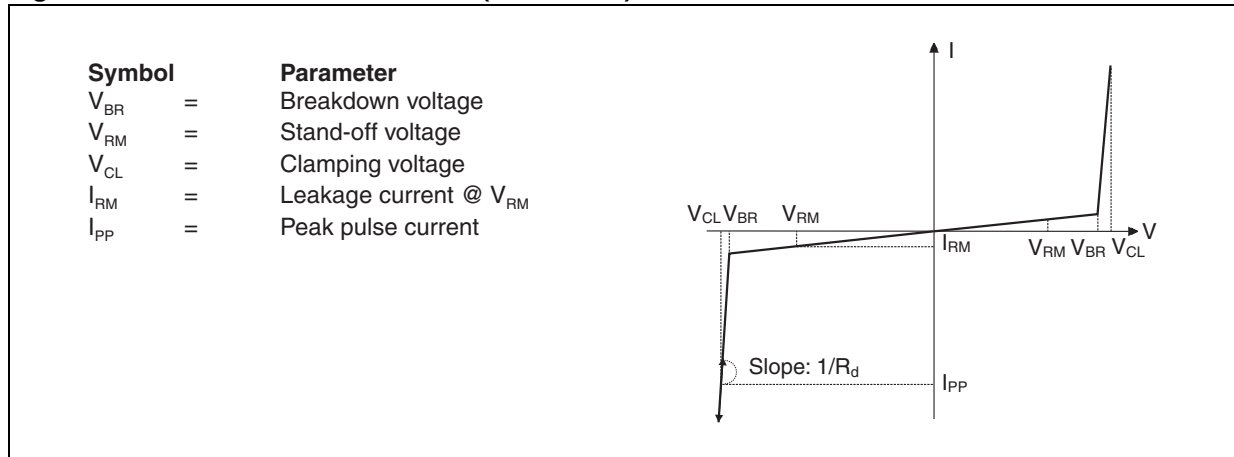


Table 2. Electrical characteristics (values, $T_{amb} = 25\text{ °C}$)

| Symbol | Parameter | Test conditions | Value | | | Unit |
|---------------|---------------------------------|---|-------|------|------|---------------|
| | | | Min. | Typ. | Max. | |
| V_{BR} | Breakdown voltage | $I_R = 1\text{ mA}$ | 0.7 | 1.0 | 1.3 | V |
| I_{RM} | Leakage Current | $V_{RM} = 100\text{ mV}$ | | | 0.3 | μA |
| $C_{i/o-i/o}$ | Capacitance between I/O and GND | $V_R = 0\text{ V}$, $F = 1\text{ MHz}$, any I/O pin to GND | | 3 | 3.5 | pF |

Figure 3. Relative variation of leakage current versus junction temperature (typical values)

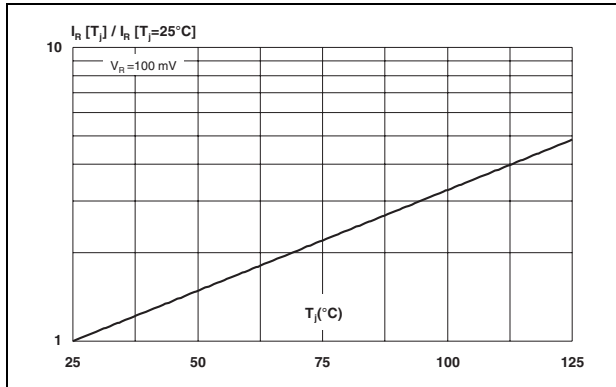


Figure 4. S21 attenuation measurements (50 Ω / 50 Ω)

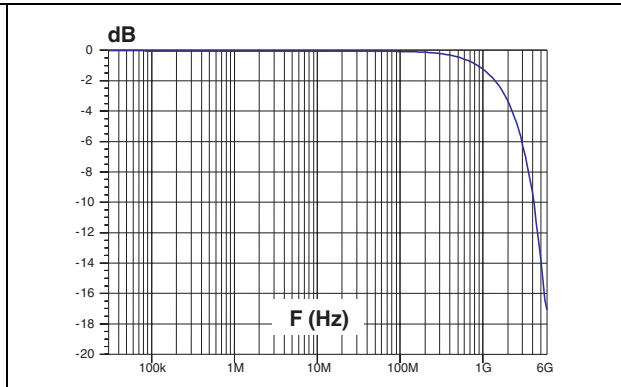


Figure 5. ESD response to IEC 61000-4-2 (+15 kV air discharge)

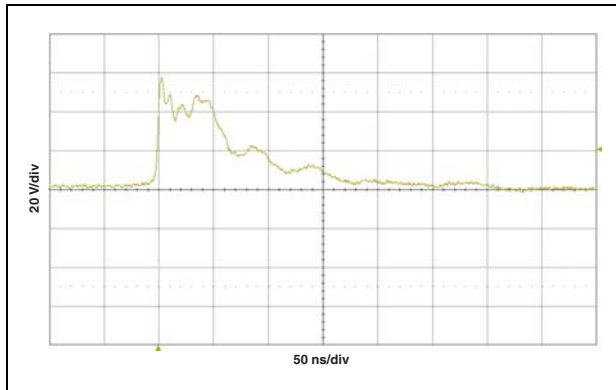


Figure 6. ESD response to IEC 61000-4-2 (-15 kV air discharge)

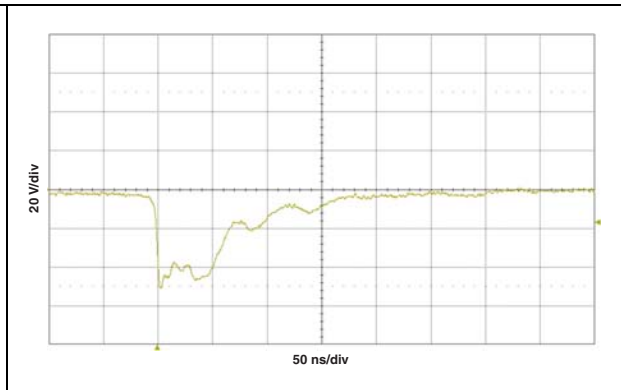
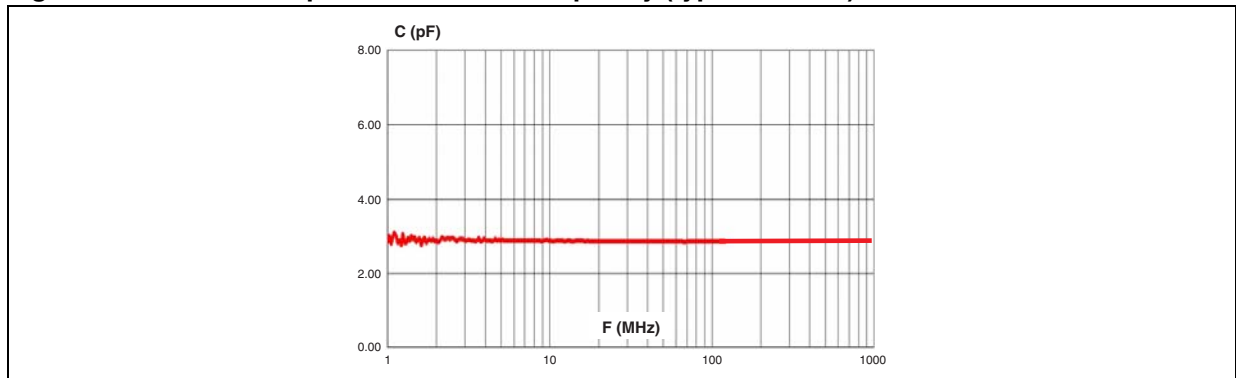
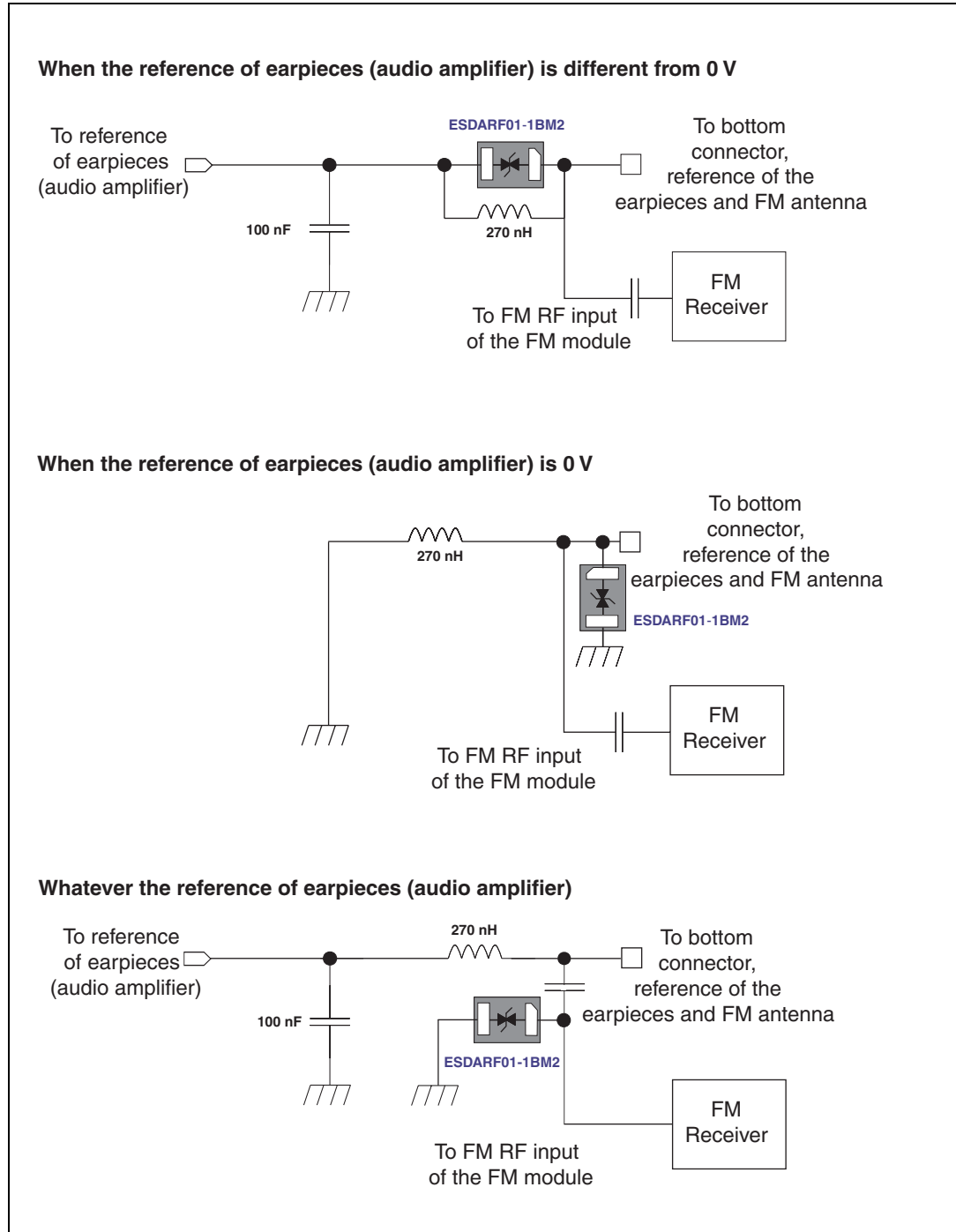


Figure 7. Junction capacitance versus frequency (typical values)



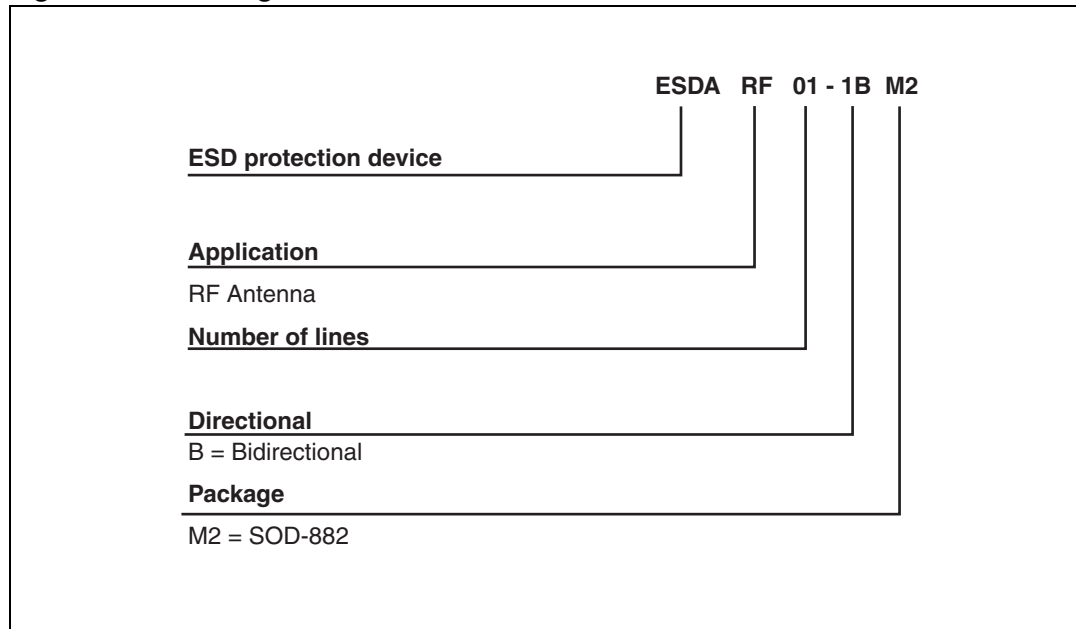
2 Application schematics

Figure 8. Application schematics



3 Ordering information scheme

Figure 9. Ordering information scheme



4 Package information

- Epoxy meets UL94, V0
- Lead-free packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Figure 10. SOD882 dimension definitions

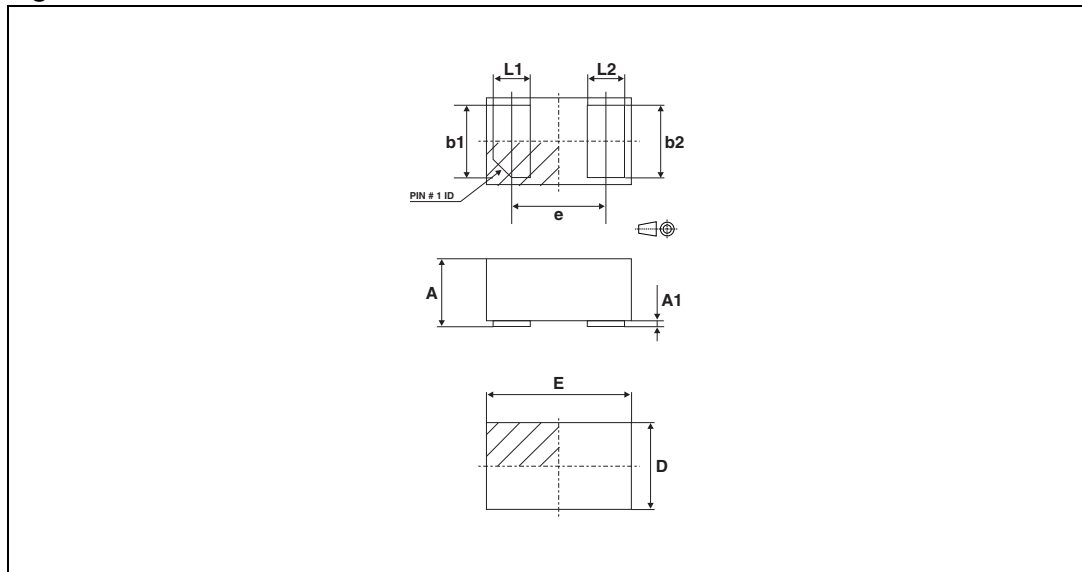


Table 3. SOD882 dimension values

| Ref. | Dimensions | | | | | |
|------|-------------|------|------|--------|-------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 0.40 | 0.47 | 0.50 | 0.016 | 0.019 | 0.020 |
| A1 | 0.00 | | 0.05 | 0.000 | | 0.002 |
| b1 | 0.45 | 0.50 | 0.55 | 0.018 | 0.020 | 0.022 |
| b2 | 0.45 | 0.50 | 0.55 | 0.018 | 0.020 | 0.022 |
| D | 0.55 | 0.60 | 0.65 | 0.022 | 0.024 | 0.026 |
| E | 0.95 | 1.00 | 1.05 | 0.037 | 0.039 | 0.041 |
| e | 0.60 | 0.65 | 0.70 | 0.024 | 0.026 | 0.028 |
| L1 | 0.20 | 0.25 | 0.30 | 0.008 | 0.010 | 0.012 |
| L2 | 0.20 | 0.25 | 0.30 | 0.008 | 0.010 | 0.012 |

Figure 11. SOD882 footprint in mm (inches)

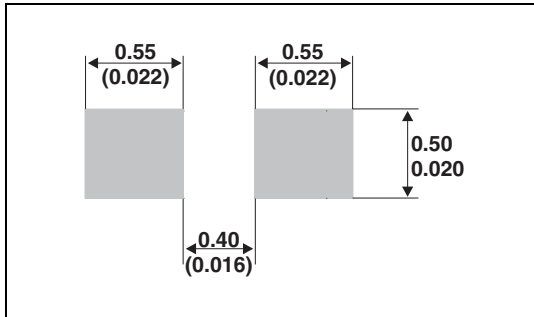
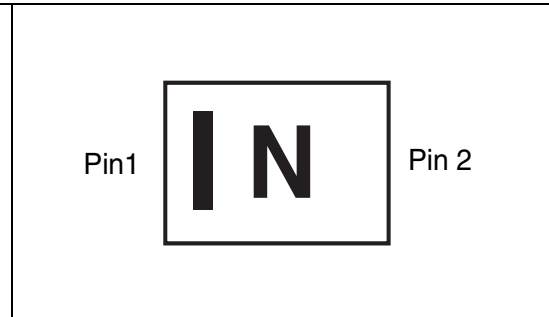
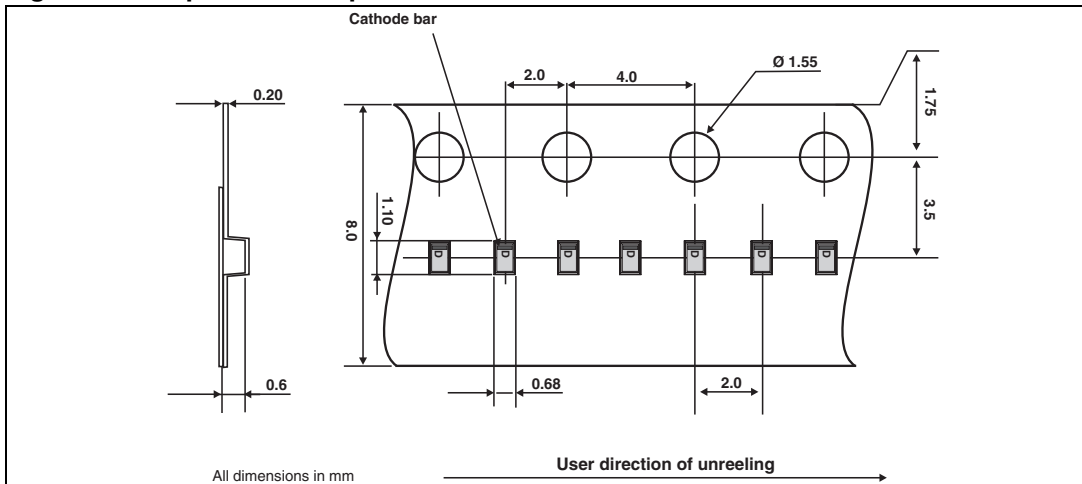


Figure 12. Marking



Note: Product marking may be rotated by 90° for assembly plant differentiation. In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.

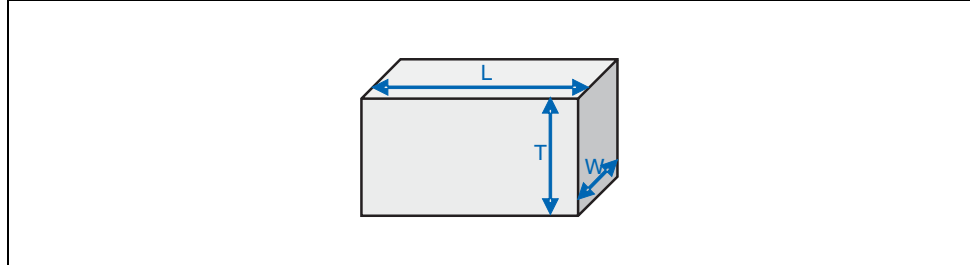
Figure 13. Tape and reel specifications



5 Recommendation on PCB assembly

5.1 Stencil opening design

1. General recommendation on stencil opening design
 - a) Stencil Opening Dimensions: L (Length), W (Width), T (Thickness).



- b) General Design Rule
Stencil thickness (T) = 75 ~ 125 μm
Aspect Ratio = $\frac{W}{T} \geq 1.5$
Aspect Area = $\frac{L \times W}{2T(L + W)} \geq 0.66$

2. Reference design
 - a) Stencil opening thickness: 100 μm
 - b) Stencil opening for leads: Opening to footprint ratio is 60% to 75%.

5.2 Solder paste

1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
2. "No clean" solder paste is recommended.
3. Offers a high tack force to resist component movement during high speed
4. Solder paste with fine particles: powder particle size is 20-45 μm .

5.3 Placement

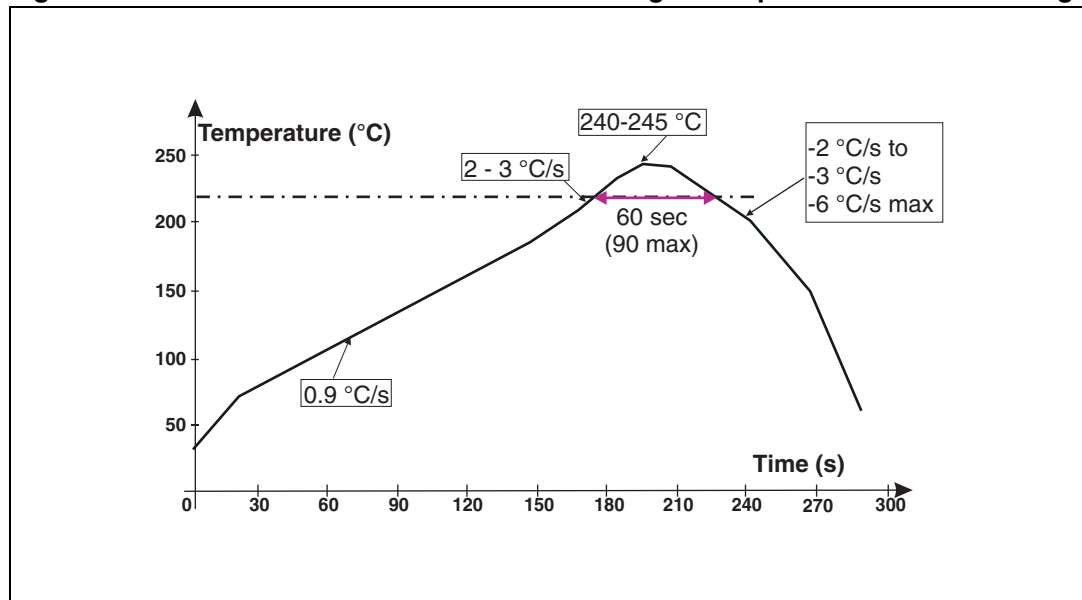
1. Manual positioning is not recommended.
2. It is recommended to use the lead recognition capabilities of the placement system, not the outline centering
3. Standard tolerance of ± 0.05 mm is recommended.
4. 3.5 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
5. To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
6. For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

5.4 PCB design preference

1. To control the solder paste amount, the closed via is recommended instead of open vias.
2. The position of tracks and open vias in the solder area should be well balanced. The symmetrical layout is recommended, in case any tilt phenomena caused by asymmetrical solder paste amount due to the solder flow away.

5.5 Reflow profile

Figure 14. ST ECOPACK[®] recommended soldering reflow profile for PCB mounting



Note: Minimize air convection currents in the reflow oven to avoid component movement.

6 Ordering information

Table 4. Ordering information

| Order code | Marking | Package | Weight | Base qty | Delivery mode |
|---------------|------------------|---------|--------|----------|---------------|
| ESDARF01-1BM2 | D ⁽¹⁾ | SOD882 | 0.9 mg | 12000 | Tape and reel |

1. The marking can be rotated by multiples of 90° to differentiate assembly location

7 Revision history

Table 5. Document revision history

| Date | Revision | Changes |
|-------------|----------|---|
| 17-Apr-2007 | 1 | First issue |
| 17-Nov-2010 | 2 | Updated Figure 4 . and updated opening to footprint ratio to 60% - 75% in Section 5: Recommendation on PCB assembly . Updated base qty in Table 4 . |
| 13-Jun-2012 | 3 | Updated Table 3 and added Figure 10 . |

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